

Electronic Patent Application Fee Transmittal

Application Number:	10773517			
Filing Date:	06-Feb-2004			
Title of Invention:	METHOD AND APPARATUS FOR RAPID COOLDOWN OF ANNEALED WAFER			
First Named Inventor/Applicant Name:	Chia-Chu Kuo			
Filer:	Richard T. Ogawa/Joy Salvador			
Attorney Docket Number:	021653-002700US			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Publ. Fee- early, voluntary, or normal	1504	1	300	300
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1400	1400

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	10	3	30
Total in USD (\$)				1730